



## Material Content Data Sheet



Sales Product Name	IPD60R385CP			Issued		28. October 2019		
MA#	MA005402439							
Package	PG-TO252-3-341			Weight*		389.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.064	1.30	1.30	12993	12993
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		176	
	non noble metal	iron	7439-89-6	0.229	0.06		588	
	non noble metal	copper	7440-50-8	228.946	58.74	58.82	587374	588138
wire	non noble metal	aluminium	7429-90-5	0.438	0.11	0.11	1123	1123
encapsulation	organic material	carbon black	1333-86-4	0.383	0.10		982	
	plastics	epoxy resin	-	11.608	2.98		29782	
	inorganic material	silicondioxide	60676-86-0	115.574	29.65	32.73	296511	327275
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9595	9595
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1305	1305
solder	non noble metal	tin	7440-31-5	0.080	0.02		206	
	noble metal	silver	7440-22-4	0.100	0.03		258	
	non noble metal	lead	7439-92-1	3.836	0.98	1.03	9842	10306
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		49	
	non noble metal	copper	7440-50-8	19.177	4.92	4.92	49201	49265
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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